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(54) Title: TECHNIQUES FOR FORMING RECESS IN SUBSTRATE AND ARTICLES INCLUDING RECESSES

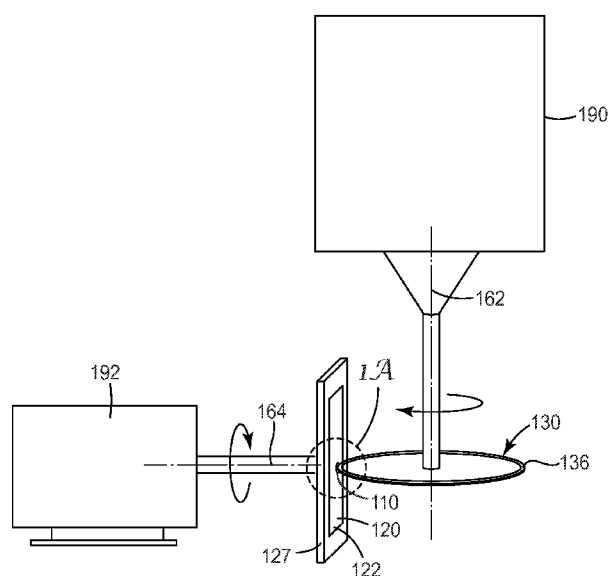


FIG. 1

(57) Abstract: An assembly may include a substrate defining at least one recess and a component located adjacent to the recess and attached to the substrate. In some examples, the recess may be formed by frictionally contacting a structured abrasive layer of an abrasive article with a surface of the substrate, longitudinally advancing the structured abrasive layer relative to the surface of the substrate, and rotating the substrate around a rotational axis substantially perpendicular to the surface of the substrate such that the structured abrasive layer maintains contact with and abrades the surface of the substrate thereby forming the recess therein. In some examples, the recess may be formed in the substrate after the component is attached to the substrate. Moreover, the recess may be formed without using added loose abrasive particles or abrasive slurry.

**Declarations under Rule 4.17:**

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